Tyrone Camarero Specifications

Camarero DS300TTP-224I

Key features

Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:

- Dual socket R3 (LGA 2011) supports Intel® Xeon® processor E5-2600v4/v3 family
- Intel® C612 chipset
- Up to 2TB ECC 3DS LRDIMM, up to DDR4-2400 MHz; 16x DIMM slots
- 1x PCI-E 3.0 x16 Low-profile slot and 1x "0 slot"
- Single port IB (FDR, 56Gbps), w/ QSFP connector
- Intel® i350-AM2 Dual port GbE LAN
- Integrated IPMI 2.0 with KVM and Dedicated LAN
- 6x 2.5" Hot-swap SATA HDD Bays
- 2000W Redundant Power Supplies Titanium Level (96%)







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Dual socket R3 (LGA 2011) supports Intel® Processor

Xeon® processor E5-2600v4/v3 family

Chipset

Intel® C612 chipset Chipset

System Memory

Memory Capacity 16x 288-pin DDR4 DIMM slots, Up to 2TB

ECC 3DS LRDIMM, 512 ECC RDIMM

Expansion Slots

PCI-Express 1x PCI-E 3.0 x16 Low-profile slot and

1x "0 slot"

Integrated On-Board

SATA SATA3 (6Gbps); RAID 0, 1, 5, 10

LAN 2x RJ45 Gigabit Ethernet LAN ports,

1x RJ45 Dedicated IPMI LAN port

Add-on Options

Raid Optional

Optical Drive None

Front Panel

LED Indicators Power status LED, HDD activity LED,

2x Network activity LEDs, Universal

Information (UID) LED

Buttons Power On/Off button, UID button

Drive Bays

HDD bays 6x 2.5" Hot-swap SAS/SATA HDD trays

Power Supply

2000W Redundant Power Supplies Titanium Level (96%)

Cooling System

4x 8cm heavy duty PWM fans with optimal fan speed control

Form Factor

Form Factor 2U Rackmount

Width 17.25"(438mm), : Height 3.47" (88mm), 28.75" (730mm) Depth

Email: info@tyronesystems.com For more/current product information, visit www.tyronesystems.com

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